MULTI-COM.PL



BGA stencil for Samsung Galaxy S5 (SM-G900F)

Product ID: 21745

Price: **6.20 EUR**

Product weight: **0.02 kg**

Description:

BGA stencil for Samsung Galaxy S5 (SM-G900F) plaiting kit it's a BGA stencil matrix needed when you have to exchange BGA parts of your phone and wan't to apply BGA balls into IC.

Go to the product

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